



RUGGED GROUND PLANE

Q2™ HIGH-SPEED INTERCONNECTS

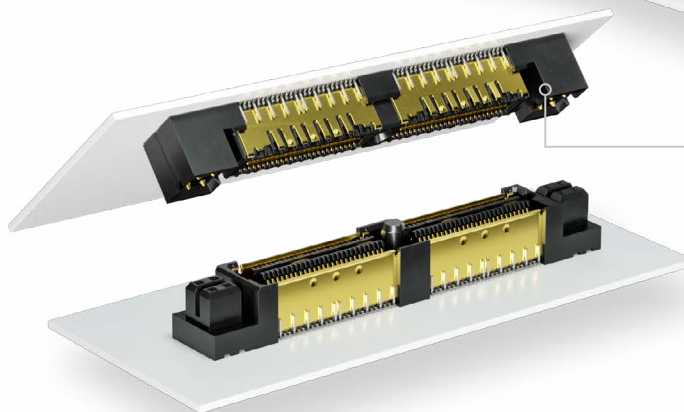
- Integral power/ground plane rated up to 15.7 A
- 0.635 mm pitch
- Increased insertion depth for rugged applications
- Up to 156 signal pins/48 signal pairs standard
- Shielding available for EMI protection (QMSS/QFSS)
- 10 – 16 mm stack heights
- Optional guide posts
- Meets PCI/104-Express™ standard specifications
- Standoffs available to aid with unmating and protect from damage (SO Series)



Vertical, right-angle and edge mount

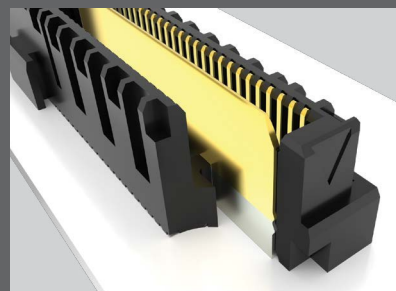


Power pins and RF options



INTEGRAL GROUND PLANE

- Surface mount ground plane between two signal rows improves electrical performance
- Significantly reduces row-to-row crosstalk
- Reduces coupling between pins within a row



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

SYSTEM

- **QMS** – 0.635 mm Ground Plane Header
- **QFS** – 0.635 mm Ground Plane Socket
- **QMSS** – 0.635 mm Shielded Ground Plane Header
- **QFSS** – 0.635 mm Shielded Ground Plane Socket

For more High-Speed Board-to-Board Solutions, please visit [samtec.com/mezzanine](https://www.samtec.com/mezzanine)